

ABSTRACT OF THE DISCLOSURE

Outstanding YAG laser marking characteristics can be obtained without electric defects such as a short circuit and
5 leak current and without deforming gold wires by using an epoxy resin composition for semiconductor sealing comprising an epoxy resin, a phenol resin, an inorganic filler, a curing accelerator, and a carbon precursor having a specific electric resistivity in a semiconductor region of 1×10^2 ·cm or more but less than
10 1×10^7 ·cm as essential components, wherein the amounts of the inorganic filler and the carbon precursor in the epoxy resin composition are respectively 65-92 wt% and 0.1-5.0 wt%.